

SDF181A/B-S Epoxy Adhesive

Technical datasheet



Description & Application

SDF181A/BS is a solvent-free environmentally friendly resin adhesive used for room temperature curing. After curing, the layer is of medium hardness, so it can withstand strong impact and vibration. The layer has good mechanical properties and corrosion resistance and can withstand temperature changes. It is widely used in the bonding and pouring of food contact products, electronic components and metals, ceramics, rubber, glass, fiber products, etc., and has excellent adhesion.

Product data

	SDF181A-S	SDF181B-S	Mixed Adhesive
Appearance	Transparent, milk, gray, black	Transparent, white, yellow, light brown	
Specific gravity	1.05	0.98	
Viscosity at 25°C (Pa.s)	8000-15.000	10.000-12.000	
Mixing Ratio (weight)	100	100	
Pot life at 25°C (100gr)			10-15min
Flash point	210°C	>240°C	
Curing Conditions			6h at 25°C 2-3h at 60°C

Processing

Working environment: Please keep the plastic container clean. A, B components are strictly according to the weight ratio, accurately weighed, and stir it evenly along the inner wall of the container clockwise until it is used for 3-5 minutes.

According to the operating time and amount of glue deployment, to avoid waste. When the temperature is lower than 15 °C, please pre-heat the A glue to 30 °C and then adjust the rubber, easy to operate (low temperature, A glue will thicken); After use must seal the lid, to avoid the product due to moisture absorption scrapped.

When the relative humidity is more than 85%, the surface of the cured product can easily absorb the moisture in the air to form a white mist. Therefore, when the relative humidity is more than 85%, it is not suitable for room temperature curing. It is recommended to use the heating and curing.

The lid must be sealed after use to avoid the product being scrapped due to moisture absorption.

Typical cured properties

Hardness	Shore D	80-82
Withstand voltage	KV/mm	20 ~22
Tensile strength	Kg/mm ²	22
Volume resistance	Ohm ³	1x10 ¹⁵
Surface resistance	Ohmm ²	1.2x10 ¹⁵
Heat-resistant temperature	°C	105
Water absorption rate	%(24h at 25°C)	<0.03
Shrinkage	%	<0.35
Compressive strength	Kg/mm ²	20 - 25